



KappZipp™ Paste Flux for Metals Other Than Aluminum 200-600°F (95-315°C)

Description

KappZipp™ paste flux is a non-acid Petrolatum-based soldering paste containing Zinc Chloride. The Petrolatum helps protect the solder joint against corrosive attack and the paste form insures that the flux stays put until soldering. Its wide activation range of 200-600°F (95-315°C) makes it ideal for field use on Copper, Brass, and Stainless Steel with virtually any heat source.

KappZipp™ paste flux meets or exceeds the acid-free specification of section 2.01.C.1.c of CTA SP 34 21 46-1 – Traction Power Cable Lugs of CTA 2012-0021.02.

KappZipp™ paste flux meets Federal Specifications O-F 506C, Type I, form A and MIL-S-6872A.

Applications

- Useful on most common metals except Aluminum and Magnesium
- Plumbing, Electrical, and Maintenance applications
- Designed specifically to work with KappZapp™, KappFree™, and KappLead™ solders on Copper, Brass, and Stainless Steel

Directions

KappZipp™ paste flux is generally applied using a flux brush. The flux is active between 200-600°F (95-315°C). Although the flux is self-cleaning, it is recommended that the parts first be cleaned with a rough surface – sand paper, emery cloth, or a clean Stainless Steel brush. For most applications, the residues can be removed with a damp rag.

However, the following cleaning steps must be followed in critical applications:

1. Degrease with an organic solvent.
2. Use as many hot deionized water rinses as necessary.

SAFETY PRECAUTIONS

KappZipp™ paste flux contains Petrolatum, Zinc Chloride. Inhalation of fumes can cause injury to the respiratory tract and skin. In case of external contact, wash with soap and water. For eyes, flush with water for 15 minutes and get immediate medical attention. If swallowed, give plenty of water or milk and call a physician. Keep out of reach of children. Do not store near heat, as Petrolatum melts at 135°F (57°C).

Properties

Technical Data	
Form:	Red Paste
Specific Gravity:	0.95-1.00
Flash Point:	540°F (285°C)
Boiling Point:	640°F (337°C)
Spread Factor:	80 Minimum
Soldering Temperature Range:	200-600°F (95-315°C)
Shelf Life:	2 years
Packaging:	3 and 8 oz. jars
*THIS PRODUCT IS RoHS & REACH COMPLIANT	

Product Variants: 3 oz., 8 oz., and 16 oz. jars